

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6224xxxx7R-G  
Typical Mass: 1 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.047	Silicon	47200	7440-21-3
	-	Arsenic	5	7440-38-2
Lead pad	0.135	Nickel	135000	7440-02-0
	0.003	Gold	3000	7440-57-5
Die attach	0.004	Silica	3900	—
	0.002	Silicone	1800	—
	0.001	Bisphenol A, diglycidyl ether	1400	1675-54-3
Bonding wire	0.047	Gold	47300	7440-57-5
Resin	0.460	Silica	460100	60676-86-0
	0.084	Epoxy Resin	83700	—
	0.084	Phenol Resin	83700	—
	0.114	Metal hydroxide	114100	—
	0.019	Silica (crystal)	19000	14808-60-7

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."